

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jong-Woo Ha</td> <td>01/25/2010</td> </tr> <tr> <td>Myung Kil Lee</td> <td>11/07/2005</td> </tr> <tr> <td>Hyun Uk Kim</td> <td>11/07/2005</td> </tr> <tr> <td>Taebok Jung</td> <td>11/07/2005</td> </tr> </tbody> </table>		Name	Execution Date	Jong-Woo Ha	01/25/2010	Myung Kil Lee	11/07/2005	Hyun Uk Kim	11/07/2005	Taebok Jung	11/07/2005
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>STATS ChipPAC Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>5 Yishun Street 23</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>768442</td> </tr> </table>		Name:	STATS ChipPAC Ltd.	Street Address:	5 Yishun Street 23	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	768442
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CORRESPONDENCE DATA											
<p>Fax Number: (408)738-0881</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: (408) 738-0592</p> <p>Email: efiling@ishimarulaw.com</p> <p>Correspondent Name: Mikio Ishimaru</p> <p>Address Line 1: Law Offices of Mikio Ishimaru</p> <p>Address Line 2: 333 W. El Camino Real, Suite # 330</p> <p>Address Line 4: Sunnyvale, CALIFORNIA 94087</p>											
ATTORNEY DOCKET NUMBER:	27-126										
NAME OF SUBMITTER:	Mikio Ishimaru										
Total Attachments: 5											

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PATENT
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ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

STACKED DIE PACKAGE SYSTEM

for which United States patent application 11/164,160, filed November 12, 2005, has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Jung Woo

Jong-Woo Ha

Jan. 25, 2010

Date

[Signature]

Witness Signature

[Signature]

Witness Signature

Heejo chi

Print Witness Name

Kiyoun Jang

Print Witness Name

Jan. 25, 2010

Date

Jan. 25, 2010

Date

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WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

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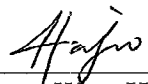
for which a United States patent application has been executed on or before the date of this assignment;

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NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
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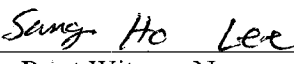
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



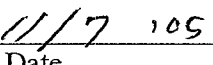
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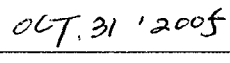
Witness Signature




Sang Ho Lee
Print Witness Name



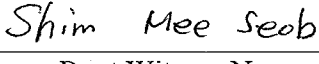
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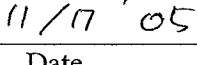
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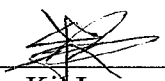


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Print Witness Name

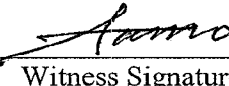


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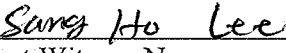
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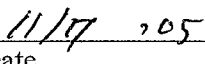
Myung Kil Lee



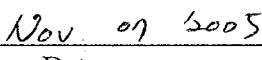
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Sang Ho Lee
Print Witness Name




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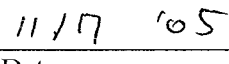
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Witness Signature




Shim Mee Seob
Print Witness Name

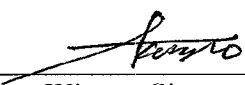


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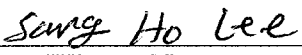
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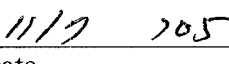
Hyun Uk Kim



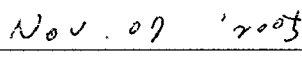
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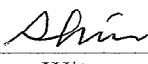
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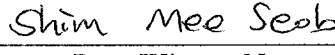
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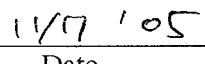
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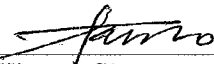
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Taebok Jung

Nov 07 ' 2005

Date



Witness Signature



Witness Signature

Suney Ho Lee

Print Witness Name

Shim Mee Seob

Print Witness Name

11/7 '05

Date

11/17 '05

Date